

TSMC-01-413C



April 15, 2004

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/810,965 03/26/04

Yen-Ming Chen et al.

NOVEL METHOD TO IMPROVE BUMP
RELIABILITY FOR FLIP CHIP DEVICE

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on April 26, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

Stephen B. Ackerman 4/26/04

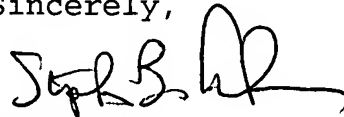
U.S. Patent 5,543,253 to Park et al., "Photomask for T-Gate Formation and Process for Fabricating the Same," discusses a dual damascene like Photo process for a T-gate.

U.S. Patent 6,042,996 to Lin et al., "Method of Fabricating a Dual Damascene Structure," discusses a dual damascene process.

The following four U.S. Patents disclose Bump and UBM processes:

- 1) U.S. Patent 6,232,212 to Degani et al., "Flip Chip Bump Bonding."
- 2) U.S. Patent 6,153,503 to Lin et al., "Continuous Process for Producing Solder Bumps on Electrodes of Semiconductor Chips."
- 3) U.S. Patent 6,130,141 to Degani et al., "Flip Chip Metallization."
- 4) U.S. Patent 6,118,180 to Loo et al., "Semiconductor Die Metal Layout for Flip Chip Packaging."

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)

TSMC-01-413C

Application Number

10/810,965

Applicant

Yen-Ming Chen et al.

Filing Date

03/26/04

Drawn by

APR 29 2004

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	TITLE	CLASS	SUBCLASS	PUBLICATION DATE IF APPROPRIATE
	5543253	8/6/96	Park et al.	439	5	12/16/94
	6042996	3/28/00	Lin et al.	430	313	4/13/98
	6232212	5/15/01	Degani et al.	438	612	2/23/99
	6153503	11/28/00	Lin et al.	438	613	3/10/98
	6130141	10/10/00	Degani et al.	438	455	10/14/98
	6118180	9/12/00	Lee et al.	257	737	11/3/97

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Portmox Pages, Etc.)

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.